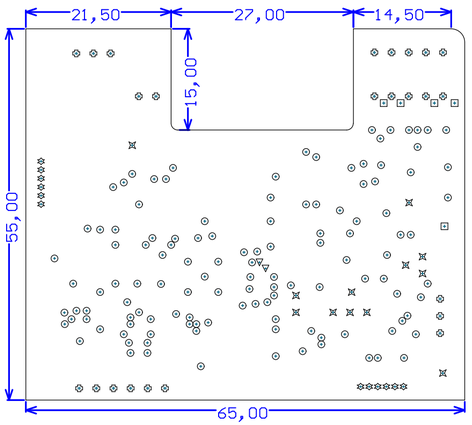
REV	ECO	Comments	Date



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
▽	2	0,500mm (19,69mil)	PTH	Round
□	5	0,400mm (15,75mil)	PTH	Round
☼	12	0,600mm (23,62mil)	PTH	Round
⌑	12	0,700mm (27,56mil)	PTH	Round
◌	24	0,900mm (35,43mil)	PTH	Round
○	123	0,350mm (13,78mil)	PTH	Round
	178 Total			

THIS PCB TO BE MANUFACTURED TO MEET ALL ACCEPTANCE LEVELS
OF A CLASS 2 PCB PER ANSI/IPC-A-600G.

MATERIAL: FR-4 or Equivalent

- [X] MULTILAYER [2] LAYERS [ ] CONTROLLED IMPEDANCE
- Cu WEIGHT EXTERNAL LAYERS [35um] FINISHED
- Cu WEIGHT INTERNAL LAYERS [N/A] FINISHED
- FINISHED OVERALL THICKNESS [1.6] mm ± [10] %
- COPPER THIEVING ALLOWED [ ] YES [X] NO

FINISH:

- [X] LEAD-FREE HOT AIR LEVELING
- [ ] IMMERSION GOLD
- [ ] IMMERSION TIN
- [ ] SMOBC WITH SELECTIVE GOLD PLATING ON LANDS INDICATED. 1um GOLD OVER 5-10 um NICKEL

SOLDERMASK [DYNACHEM EPIC 200 LPI OR EQUIVALENT]

SOLDERMASK COLOR [GREEN HIGH GLOSS]

SILKSCREEN COLOR [WHITE]

ALL HOLES TO BE LOCATED BY THE COORDINATES FROM THE NC DRILL DATA PROVIDED.

USE ARTWORK SET NO. [05-10463] PCB REV [1]

ALL UL LOGO, MANUFACTURER'S ID, AND DATE CODES SHALL BE PLACED
ON THE BOTTOM SIDE UNLESS OTHERWISE INDICATED.

ANY ALTERNATIVES TO THE ABOVE SPECIFICATIONS MUST FIRST BE APPROVED.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Paste				
2	Top Overlay				
3	Top Solder	Solder Resist	0.010mm	3.5	
4	Top Layer	Copper	0.036mm		
5	Dielectric1	FR-4	1.500mm	4.8	
6	Bottom Layer	Copper	0.036mm		
7	Bottom Solder	Solder Resist	0.010mm	3.5	
8	Bottom Overlay				
9	Bottom Paste				

MICROCHIP
Microchip Technology Inc.
2355 W. Chandler Blvd.
Chandler, AZ 85224

TITLE: DV102014 Development Kit

PART NUMBER: DV102014

PCB DESIGNER:	GERBER FILE:		
m91470	Fab Drawing (Bottom,Top Layer)		
ENGINEER:	BOARD NUMBER:	DOCUMENT NUMBER:	DATE:
m91470	04-10463	04-10463 -D	12.11.2015
PCB FILE NAME: Board 02-10463.PcbDoc	LAYER NAME: FAB (M4) NOTES (M1)	REV: 1	10mm 400mil